MEPTEC2018

HOSTED BY NEXTFLEX

A Special One-Day Event Presented By MEPTEC

NEW GENERATION FLEXIBLE HYBRID ELECTRONICS

Cost-effective Assembly & Packaging Technologies

THURSDAY, APRIL 26, 2018 | 8:00AM - 5:00PM

NEXTFLEX FACILITY | SAN JOSE, CALIFORNIA

Unlike computers and mobile phones, the Internet of Things demands a wide range of different functions in different products, and most of them need flexibility, thinness, and ultralow power consumption. These requirements can only be satisfied with new methods of packaging.

This event will explore the market opportunities, emerging applications, and materials and process requirements to provide this functionality at an affordable cost. You'll hear from experts in polymers and other flexible materials, effects of complex packaging structures on signal integrity, speed and power consumption, and the latest and most promising technology for heterogeneous packaging. Topics will also include cutting edge/niche concepts in medical implantable devices and "synthetic skin", etc.

The challenges include:

- **Handling and protecting thin and small components made from brittle materials (silicon, III-V compounds, etc.)**
- **Flexible interconnects on a wide range of scales from microns to millimeters**
- **Reliability with thermal expansion coefficients of different components ranging from a few ppm to hundreds**
- **Cost-effective process techniques for putting it all together**

REGISTER TO ATTEND TODAY!

SPONSORSHIP OPPORTUNITIES ARE AVAILABLE FOR THIS EVENT

INDUSTRY SPONSORS

SMART MICROSYSTEMS™

CONTACT US

MEPTEC THE NEXT GENERATION